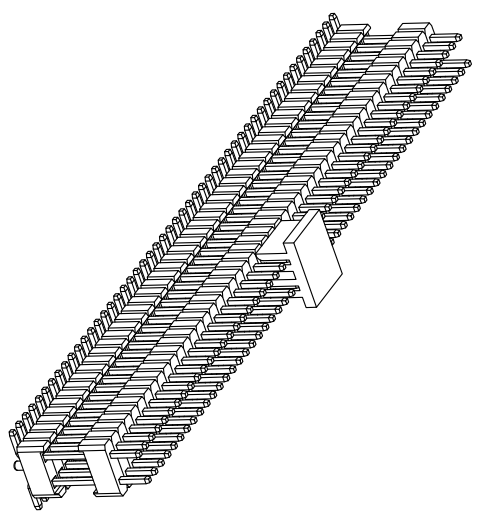
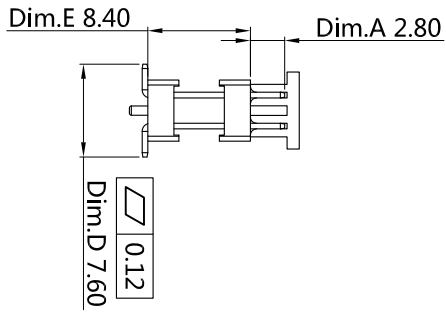
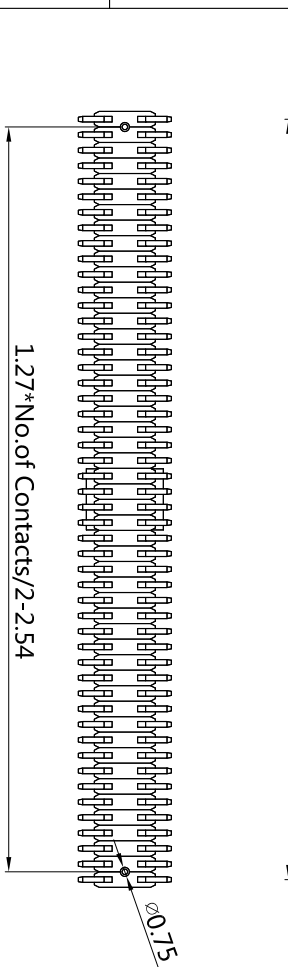
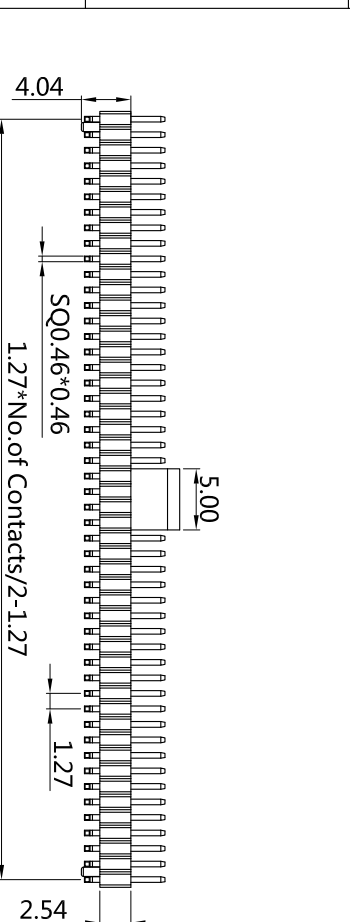
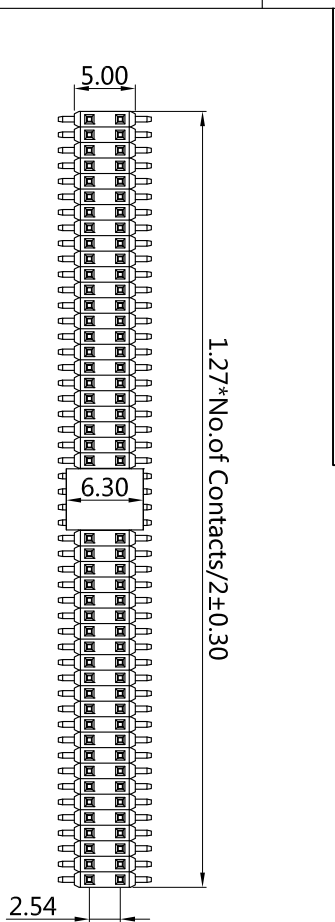
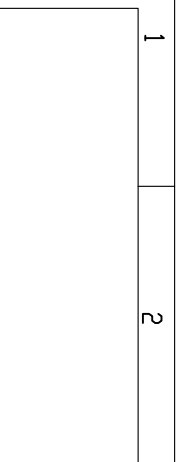
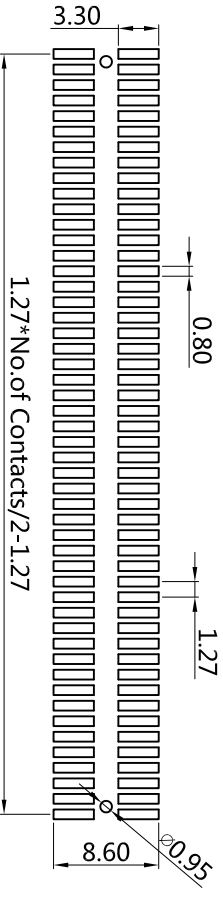


1 2 3 4 5 6 7 8



**Current Rating:** 1 Amps  
**Insulator Resistance:** 1000 Megohms min  
**Dielectric Withstanding:** AC 300V  
**Contact Resistance:** 20mΩ MAX  
**Operation Temperature:** -40~+105°C  
**Max processing temp:** 230°C for 60seconds  
**Max processing temp:** 260°C for 10seconds  
**Contact Material:** Brass  
**Insulator material:** Standard: Polyester, UL 94V-0  
**Standard:** PA6T  
**Finish:** Tin Gold Plated  
**Standard:** Gold Flash all over

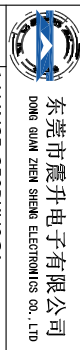
Recommended P.C. Board  
SMD Layout



(RoHS Compliant) H4 X 25 - 2 XX D1 BK X 000 E

1. Insulator material: 5. Contact Plated: 6. Special Options

- N=PA6T T=Matte Tin over Nickel I=Gold 1μ"
- L=LCP P=PA9T W=Matte Tin over nickel 150μ" E=Gold 5μ"
- 2. Circuits:2-50 PIN Y=Bright Tin over Nickel G=Gold 10μ"
- 3. Tail Style: F=Gold Flash, Matte Tin 100μ" J=Gold 10μ"
- D1=SMT+Pillars A=Gold 3μ" L=Gold 15μ"
- 4. Color: B=Gold 3μ" M=Gold 15μ" U=Gold 30μ"
- BK=Black D=Gold 5μ" V=Gold 30μ"



东莞市震升电子有限公司  
DONG GUAN ZHEN SHENG ELECTRONICS CO., LTD

BOM	1:1H4N25-250BKHC04	DRAWING NO	ZS-00206-P	EDITION:A1	ITEM: H4
	2:SQ0.46-13.7-X-C12	DRAWN BY	Deng jin quan	2021-12-22	SCALE:1:1
	3:H4N-CAP-H0-C4	APPROVAL BY	Chen xiao guang	2021-12-25	UNIT:M.M

F E D C B A

1 2 3 4 5 6 7 8

F E D C B A

F E D C B A